

ITW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 5528**
Etsuko NAKAMURA et al. : Docket No. 2003_1698A
Serial No. 10/721,164 : Group Art Unit 1752
Filed November 26, 2003 : Examiner Amanda C. Walke



LOWER LAYER MATERIAL FOR WIRING,
EMBEDDED MATERIAL, AND WIRING
FORMATION METHOD

RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action dated March 15, 2005.